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## P-Channel Enhancement-Mode Vertical DMOS FET

#### **Features**

- ▶ Free from secondary breakdown
- ► Low power drive requirement
- Ease of paralleling
- ► Low C<sub>ISS</sub> and fast switching speeds
- ► High input impedance and high gain
- Excellent thermal stability
- Integral source-to-drain diode

#### **Applications**

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

### **General Description**

This low threshold, enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

#### **Ordering Information**

Part Number	Package Option	Packing		
VP3203N3-G	3-Lead TO-92	1000/Bag		
VP3203N3-G P002				
VP3203N3-G P003		2000/Reel		
VP3203N3-G P005	3-Lead TO-92			
VP3203N3-G P013				
VP3203N3-G P014				
VP3203N3-G	TO-243AA (SOT-89)	2000/Reel		

<sup>-</sup>G denotes a lead (Pb)-free / RoHS compliant package.

### **Absolute Maximum Ratings**

Parameter	Value
Drain-to-source voltage	BV <sub>DSS</sub>
Drain-to-gate voltage	$BV_{DGS}$
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

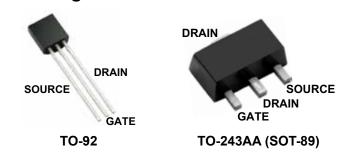
### **Typical Thermal Resistance**

Package	$oldsymbol{ heta}_{j_{oldsymbol{a}}}$
TO-92	132°C/W
TO-243AA (SOT-89)	133°C/W

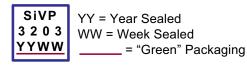
### **Product Summary**

BV <sub>DSS</sub> /BV <sub>DGS</sub>	R <sub>DS(ON)</sub> (max)	l <sub>D(ON)</sub> (min)
-30V	0.6Ω	-4.0A

### **Pin Configuration**

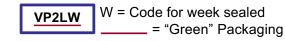


### **Product Marking**

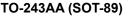


Package may or may not include the following marks: Si or 🌎

TO-92



Package may or may not include the following marks: Si or 🎲



Contact factory for Wafer / Die availablity.

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

#### **Thermal Characteristics**

Package	Ι <sub>D</sub> (continuous) <sup>†</sup>	<sub>D</sub> (pulsed)	Power Dissipation @T <sub>A</sub> = 25°C	l <sub>DR</sub> †	l <sub>DRM</sub>	
TO-92	-650mA	-4.0A	0.74W	-650mA	-4.0A	
TO-243AA (SOT-89)	-1100mA	-4.0A	1.6 <sup>‡</sup>	-1100mA	-4.0A	

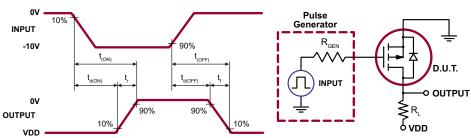
## **Electrical Characteristics** (T<sub>A</sub> = 25°C unless otherwise specified)

Sym	Parameter		Min	Тур	Max	Units	Conditions
BV <sub>DSS</sub>	Drain-to-source breakdown voltage	-30	-	-	V	$V_{GS} = 0V, I_D = -10mA$	
$V_{\rm GS(th)}$	Gate threshold voltage	-1.0	-	-3.5	V	$V_{GS} = V_{DS}$ , $I_{D} = -10$ mA	
$\Delta V_{GS(th)}$	Change in V <sub>GS(th)</sub> with temperature		ı	-	-5.5	mV/°C	$V_{GS} = V_{DS}$ , $I_{D} = -10$ mA
I <sub>GSS</sub>	Gate body leakage		-	-1.0	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
			-	-	-10	μΑ	$V_{GS} = 0V, V_{DS} = Max Rating$
I <sub>DSS</sub>	Zero gate voltage drain current	ı	-	-1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$ , $T_A = 125$ °C	
I <sub>D(ON)</sub>	On-state drain current	ı	-14	-	Α	$V_{GS} = -10V, V_{DS} = -5.0V$	
		TO-92	-	-	1.0		$V_{GS} = -4.5V, I_{D} = -1.5A$
D	Static drain-to-source on-state resistance	SOT-89	-	-	1.0	Ω	$V_{GS} = -4.5V, I_{D} = -750mA$
R <sub>DS(ON)</sub>		TO-92	-	-	0.6		$V_{GS} = -10V, I_{D} = -3.0A$
		SOT-89	ı	-	0.6		$V_{GS} = -10V, I_{D} = -1.5A$
$\Delta R_{DS(ON)}$	Change in R <sub>DS(ON)</sub> with temperature		-	-	1.0	%/°C	$V_{GS} = -10V, I_{D} = -1.5A$
G <sub>FS</sub>	Forward transductance		1000	2000	-	mmho	$V_{DS} = -25V, I_{D} = -2.0A$
C <sub>ISS</sub>	Input capacitance		-	200	300		$V_{GS} = 0V$
C <sub>oss</sub>	Common source output capacitance		-	100	120	pF	$V_{DS} = -25V,$
C <sub>RSS</sub>	Reverse transfer capacitance		-	45	60		f = 1.0MHz
t <sub>d(ON)</sub>	Turn-on delay time		-	-	10		
t <sub>r</sub>	Rise time	-	-	15	ns	$V_{DD} = -25V,$	
t <sub>d(OFF)</sub>	Turn-off delay time			-	25	113	$I_{D} = -2.0A,$ $R_{GEN} = 10\Omega$
t <sub>f</sub>	Fall time	-	-	25		OLN	
$V_{\text{SD}}$	Diode forward voltage drop	-	-	-1.6	V	$V_{GS} = 0V, I_{SD} = -1.5A$	
t <sub>rr</sub>	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = -1.0A$	

#### Notes:

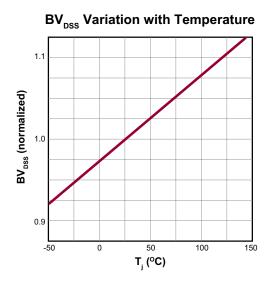
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

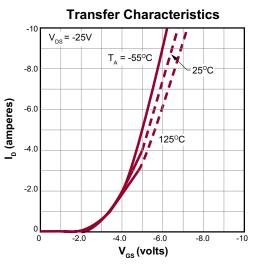
## **Switching Waveforms and Test Circuit**

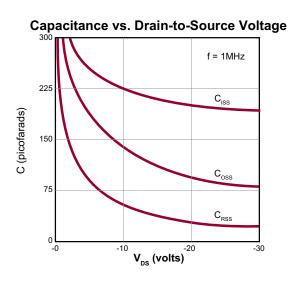


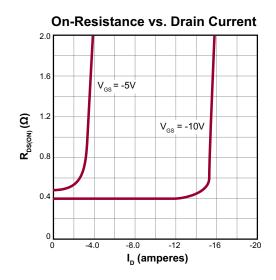
 $I_{\scriptscriptstyle D}$  (continuous) is limited by max rated  $T_{\scriptscriptstyle j}$  . Mounted on FR5 board, 25mm x 25mm x 1.57mm.

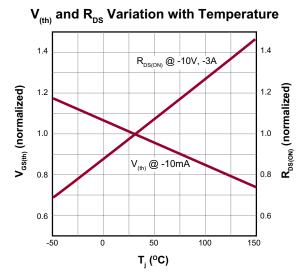
### **Typical Performance Curves**

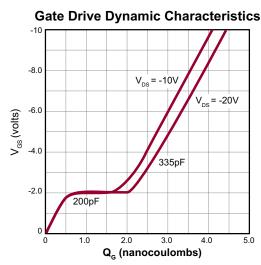




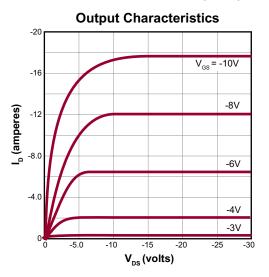


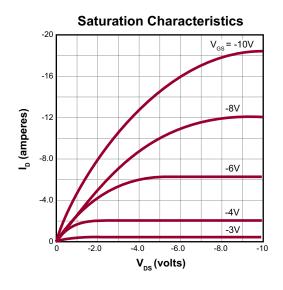


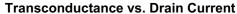


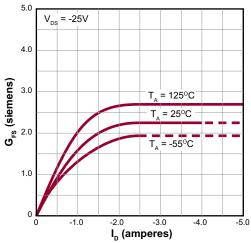


#### **Typical Performance Curves** (cont.)

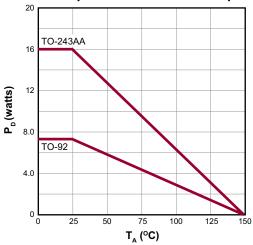




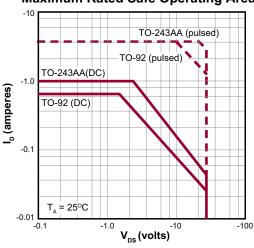




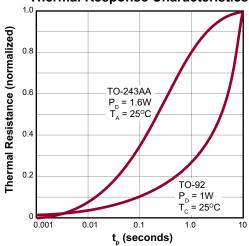




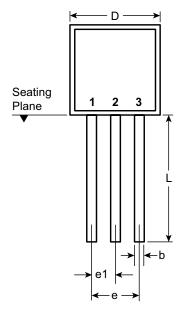
#### **Maximum Rated Safe Operating Area**

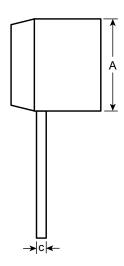


#### **Thermal Response Characteristics**



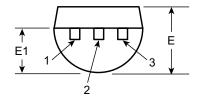
# 3-Lead TO-92 Package Outline (N3)





**Front View** 

**Side View** 



**Bottom View** 

Symb	ol	Α	b	С	D	Ε	E1	е	e1	L
	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(inches)	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

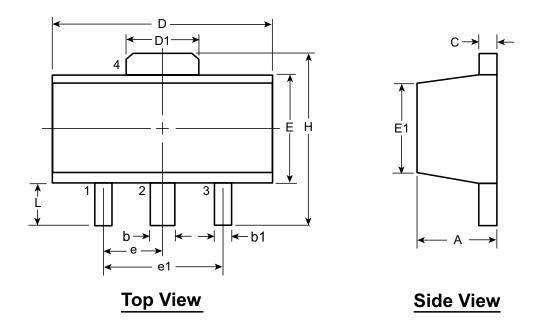
Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

<sup>\*</sup> This dimension is not specified in the JEDEC drawing.

<sup>†</sup> This dimension differs from the JEDEC drawing.

## 3-Lead TO-243AA (SOT-89) Package Outline (N8)



Symbo	ol	Α	b	b1	С	D	D1	E	E1	е	e1	Н	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00 <sup>†</sup>			3.94	0.73 <sup>†</sup>
	NOM	-	-	-	-	-	-	-	-		3.00 BSC	-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29		200	4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

† This dimension differs from the JEDEC drawing

Drawings not to scale.

Supertex Doc. #: DSPD-3TO243AAN8, Version F111010.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="http://www.supertex.com/packaging.html">http://www.supertex.com/packaging.html</a>.)

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